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Divisional of US Patent 6,221,682 (09/321,565)

Applicant: Steve M. Danziger, et al.

Art Unit: 2829

Filed: April 12, 2001

Examiner: Evan T. Pert

Docket No: L/M-102-DIV

Customer No: 28892

For: Method and Apparatus for Evaluating a Known Good Die Using
Both Wire Bond and Flip-Chip Interconnects

SUBMISSION OF PETITION

US Patent and Trademark Office
Customer Service Window / Mail Stop: Petition
Randolph Building
401 Dulany Street
Alexandria, VA 22314


Sir:

Enclosed are the following items for filing with the above-referenced patent:

1. Petition for Correction of name of Assignee on Patent (in triplicate)
2. Request for Correction Under 37 CFR § 1.323
3. Check to cover the petition fee of \$130.00 and \$100.00 fee for Certificate of Correction in the total amount of \$230.00

The Commissioner is hereby authorized to charge any deficiency or credit any overpayment to Deposit Account 19-2816. A duplicate copy of this Transmittal is attached.

Respectfully submitted,


Ronald R. Snider
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Date: September 26, 2005

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